

Ratcheting Induced Slow Crack (RISC)

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Harvard University

Work with

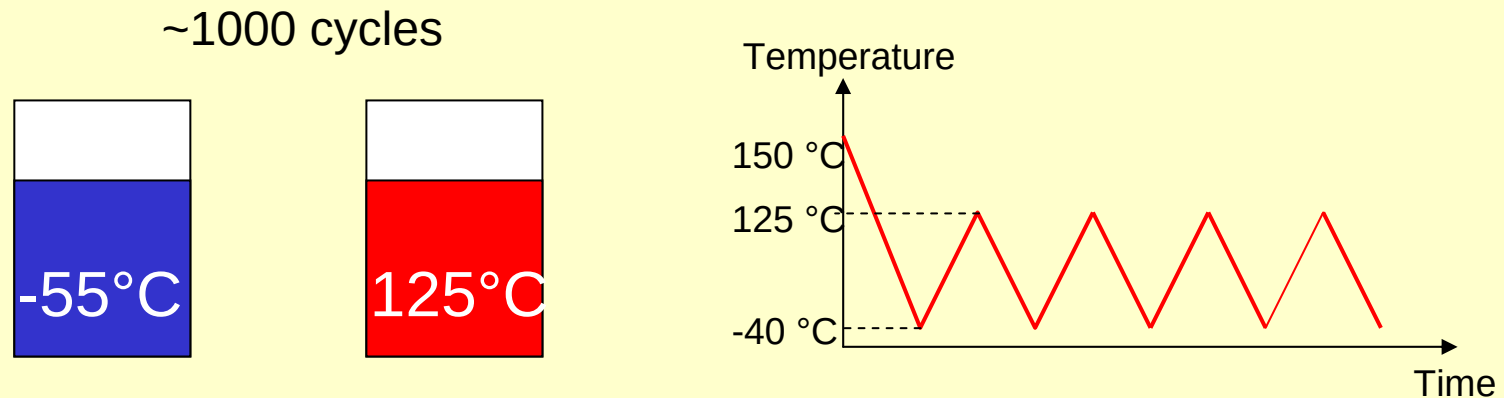
MIN HUANG, Rui Huang, Jim Liang, Jean Prevost

Princeton University

Q. MA, H. Fujimoto, J. He

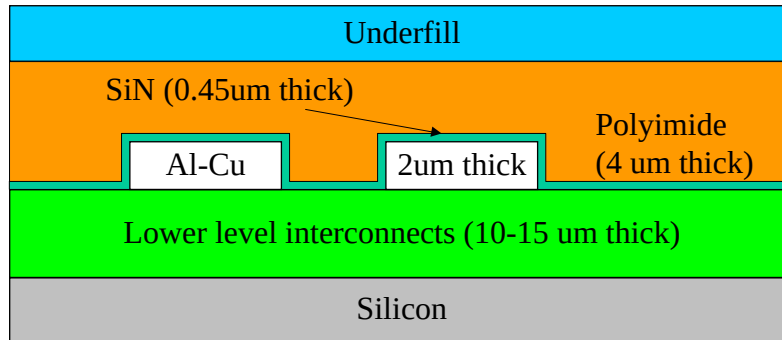
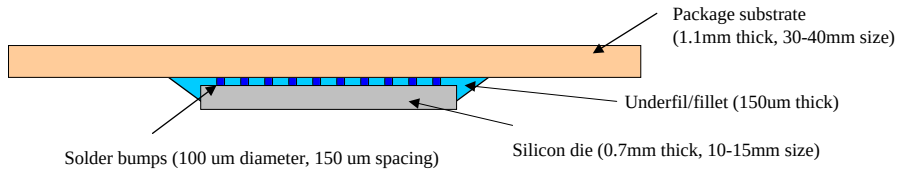
Intel Corporation

Thermal Cycling: Qualification Test

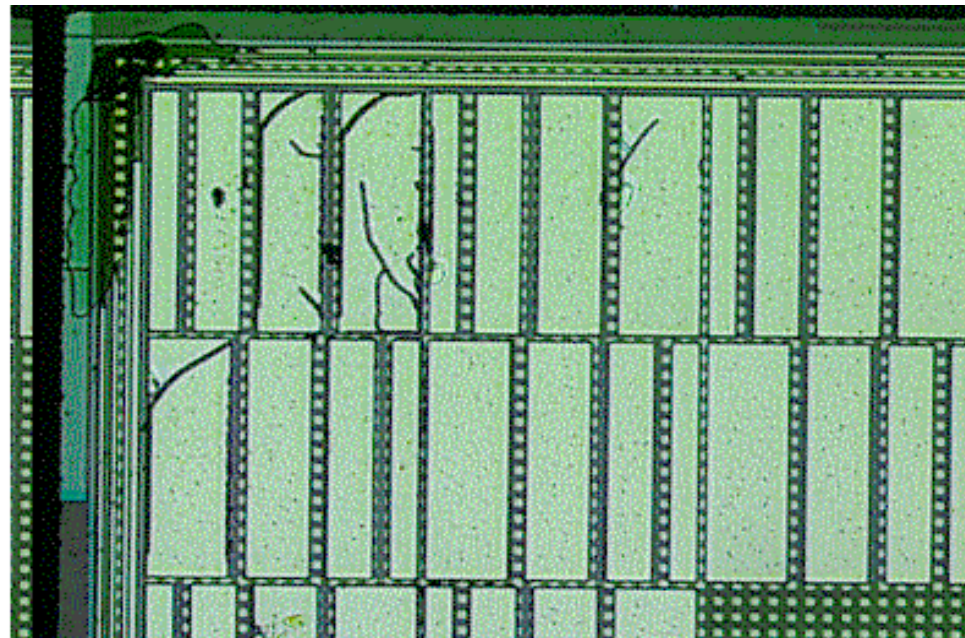
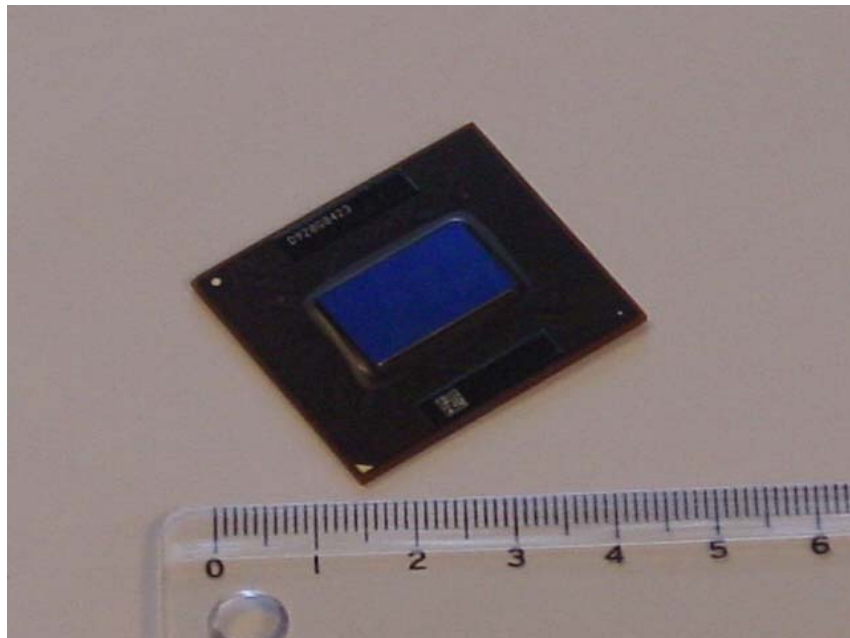
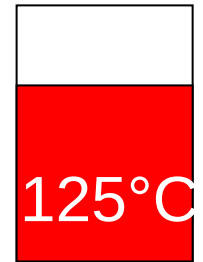
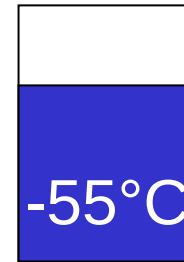


- Make-and-break
- Time consuming, a **bottleneck**
- Multiple failure modes
- Little understanding of mechanisms
- **New materials**

Flip-chip structure

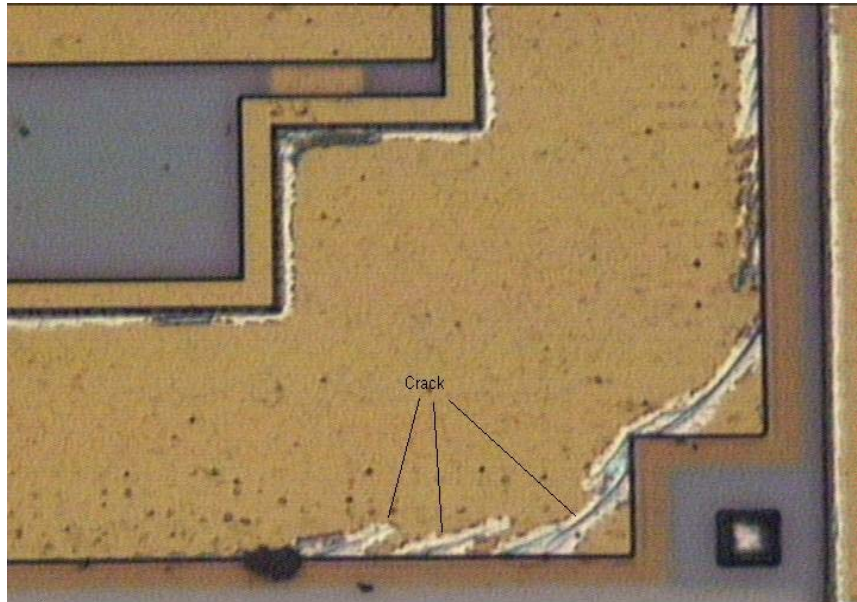


~1000 cycles

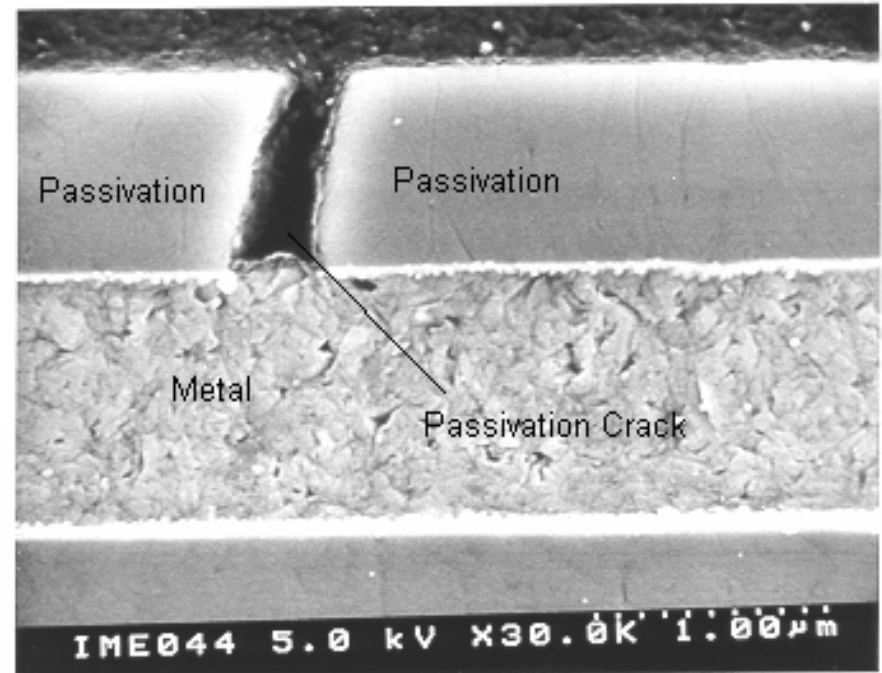


500 cycles between -55°C and 125°C

Plan view



Edge view



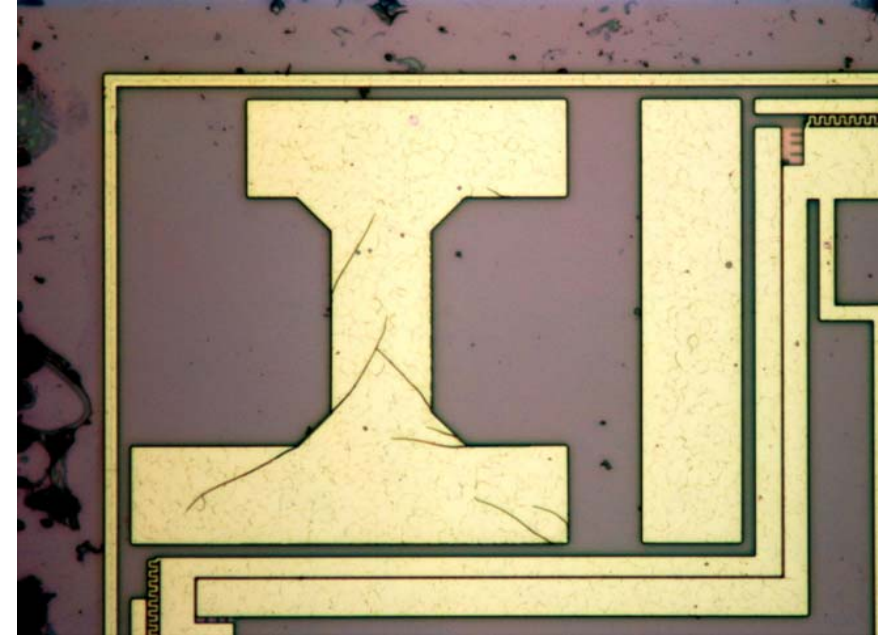
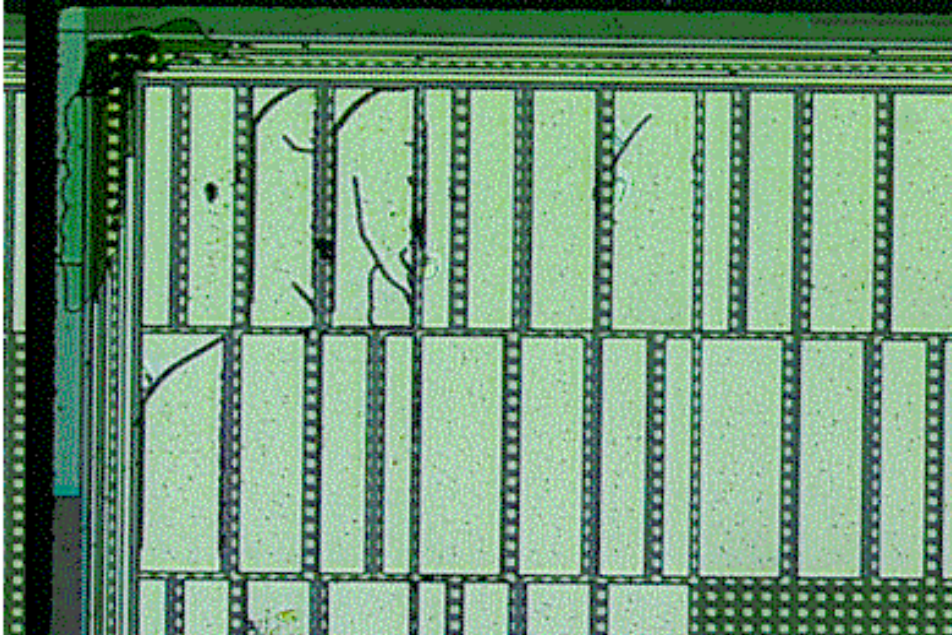
Courtesy of Dr. **J.B. Han** , Agilent Technologies Singapore

Empirical Observations of Cracking

- At die corners
- After temperature cycles
- In SiN film over Al pads, but not in SiN film over silica
- More likely when Al pad is wide

Organic substrate

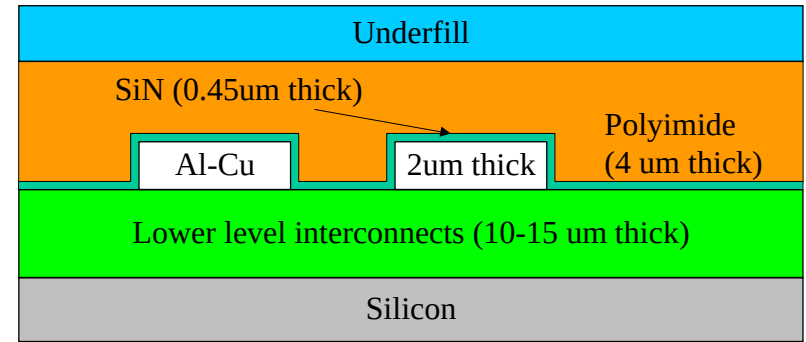
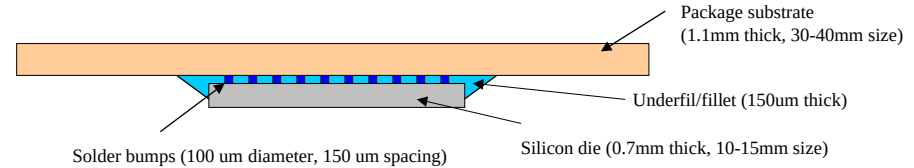
Silicon die



Questions

- **Why cycling?**
SiN does not fatigue

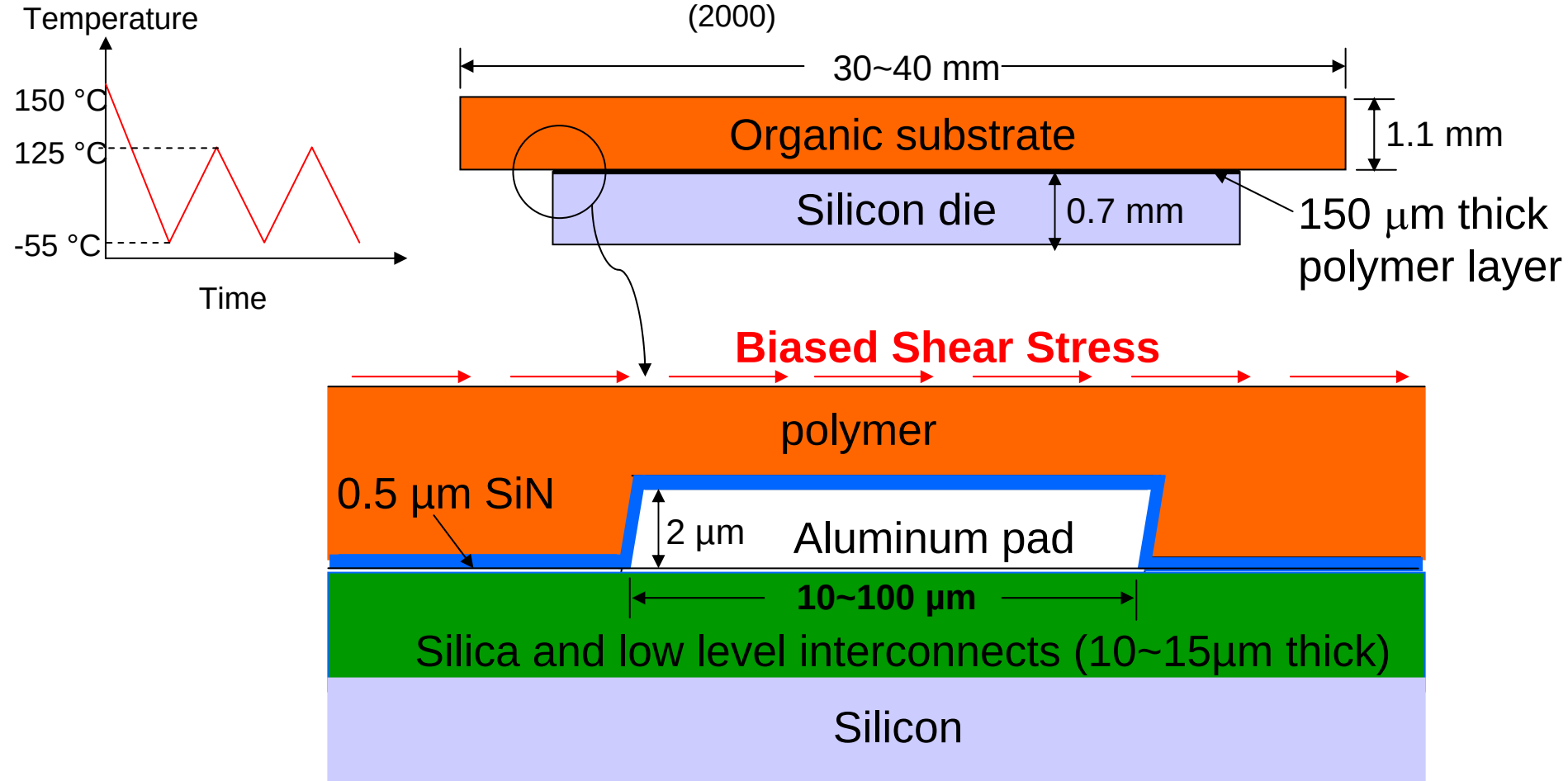
Flip-chip structure



- **Why cracking?**
- * Shear stress is limited by the yield strength of polymer, say 100 MPa.
- * Breaking strength of SiN is 1000 MPa.

Ratcheting Plastic Deformation

Huang, Suo, Ma, Fujimoto, *J. Mater. Res.*, **15**, 1239 (2000)

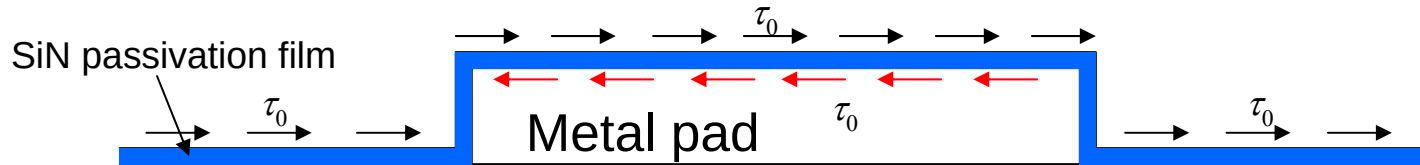


- **Biased shear stress, from organic substrate**

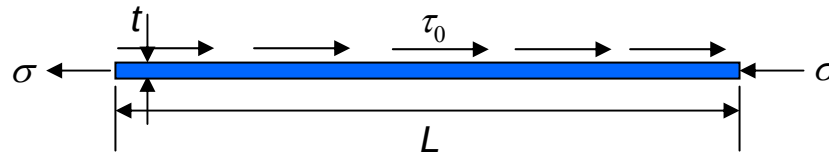
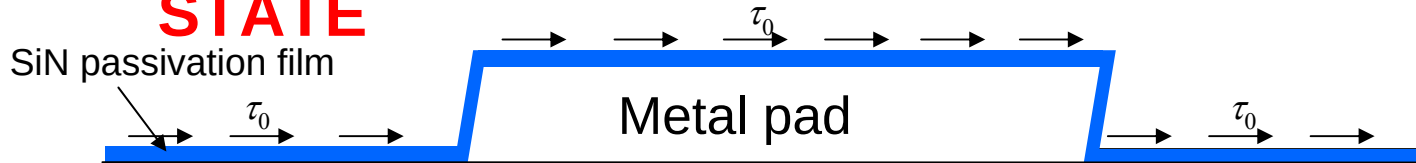
- **Metal yields from CTE mismatch with**

Stress builds up in SiN. **STEADY STATE**

First cycle

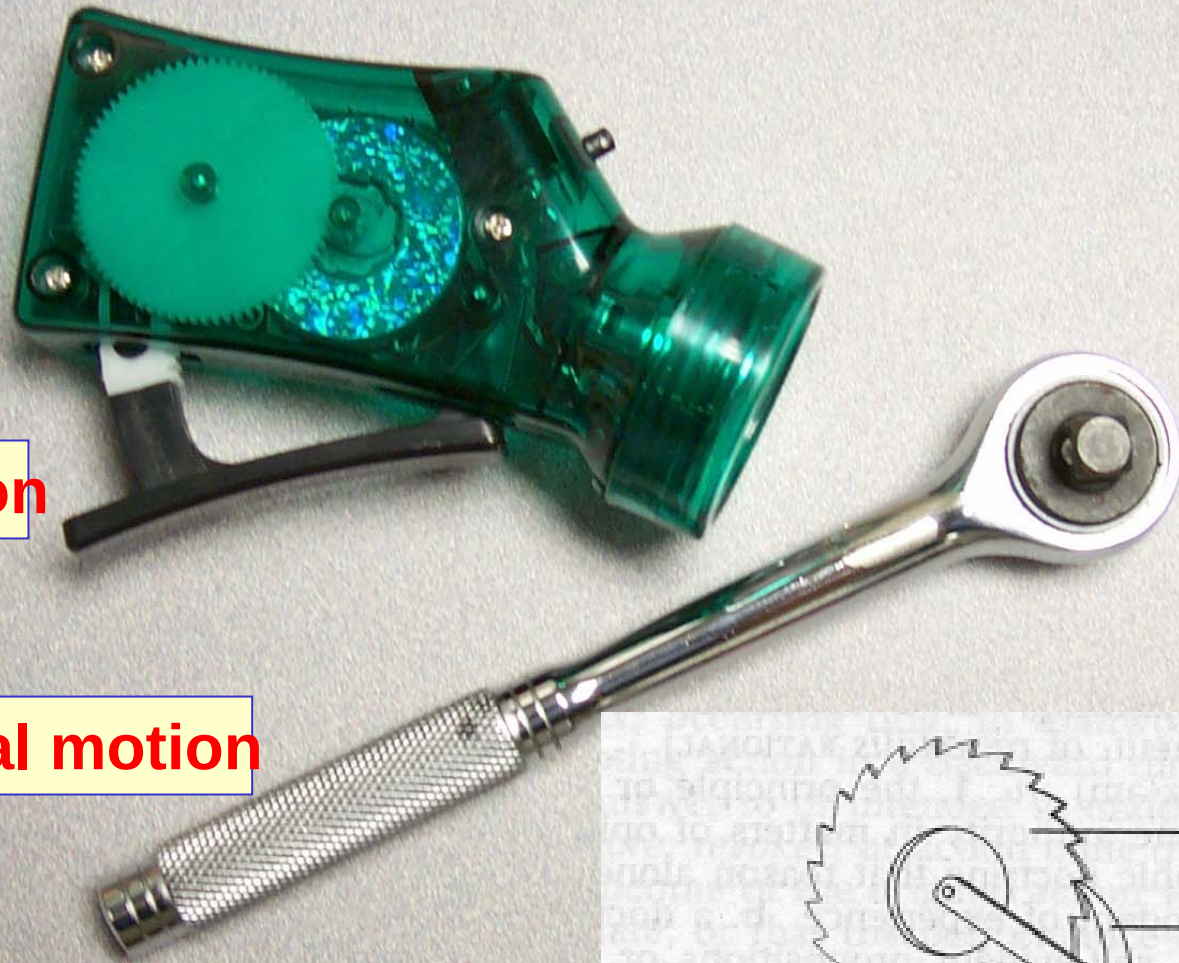


Many cycles, **STEADY STATE**



$$2\sigma t = \tau_0 L$$
$$\sigma = \frac{\tau_0 L}{2t}$$

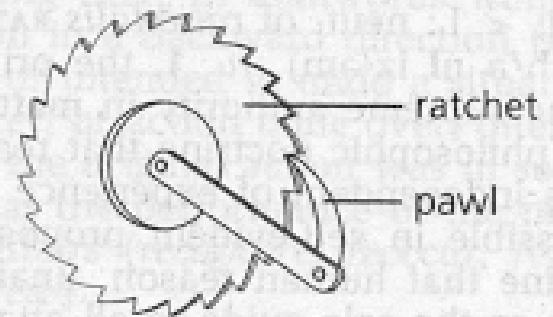
Ratchet and Pawl



Cyclic motion

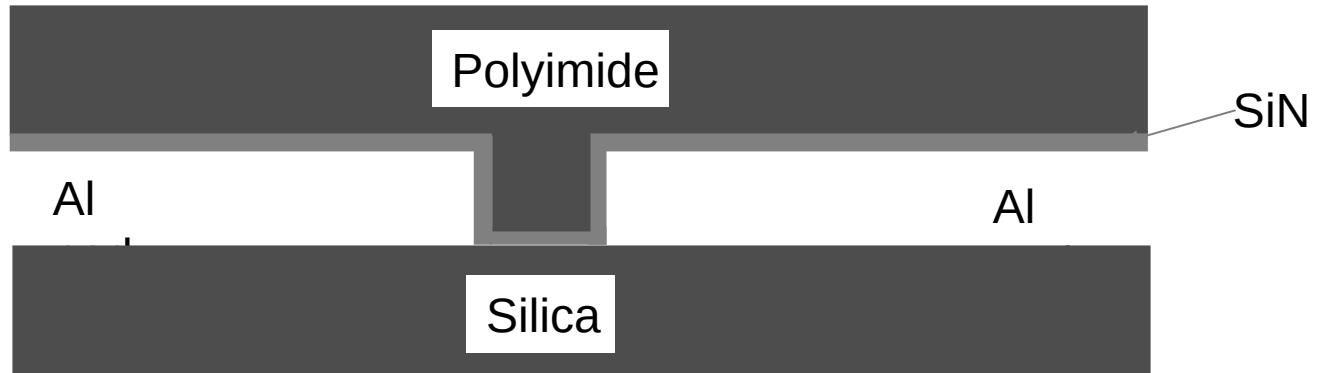


One-directional motion

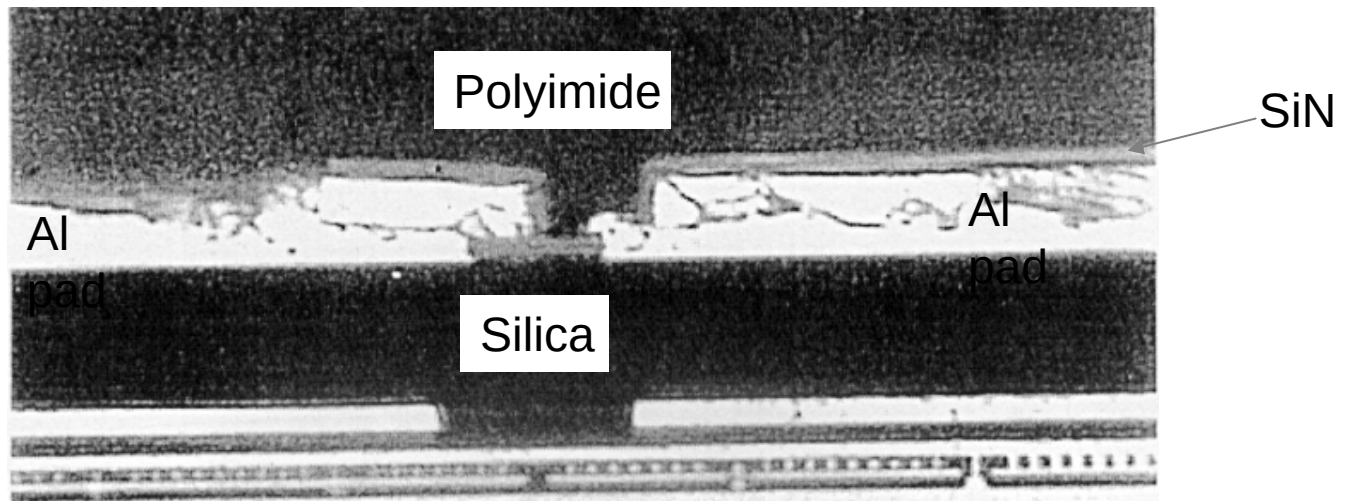


ratchet wheel

Metal Pad **Crawling**



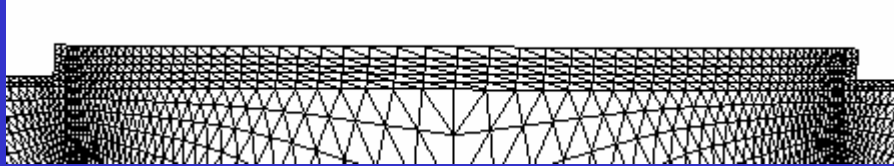
↓ After ~1000 thermal cycles



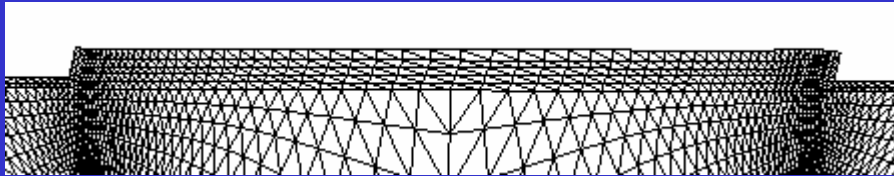
Large plastic deformation over many thermal cycles

Finite Element Simulation

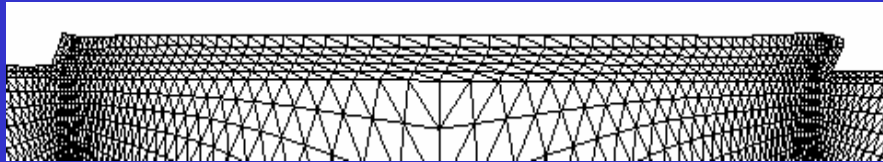
1 cycle



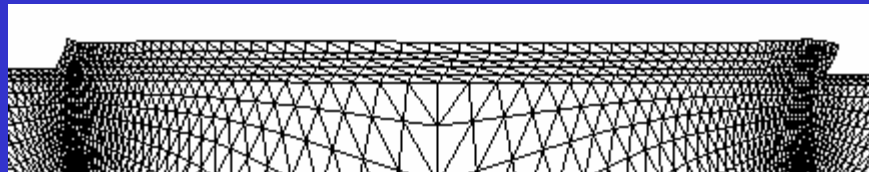
10 cycles



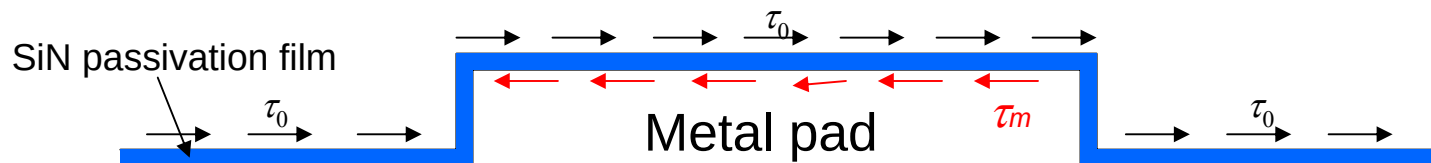
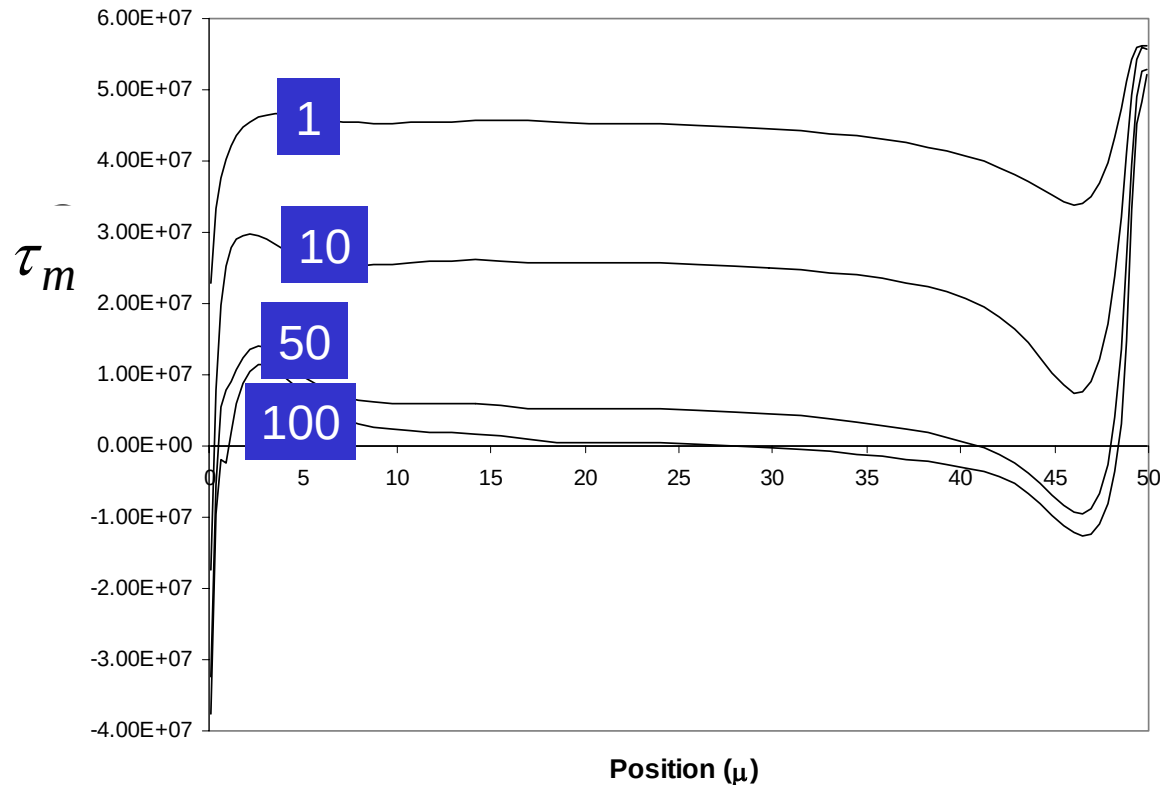
50 cycles



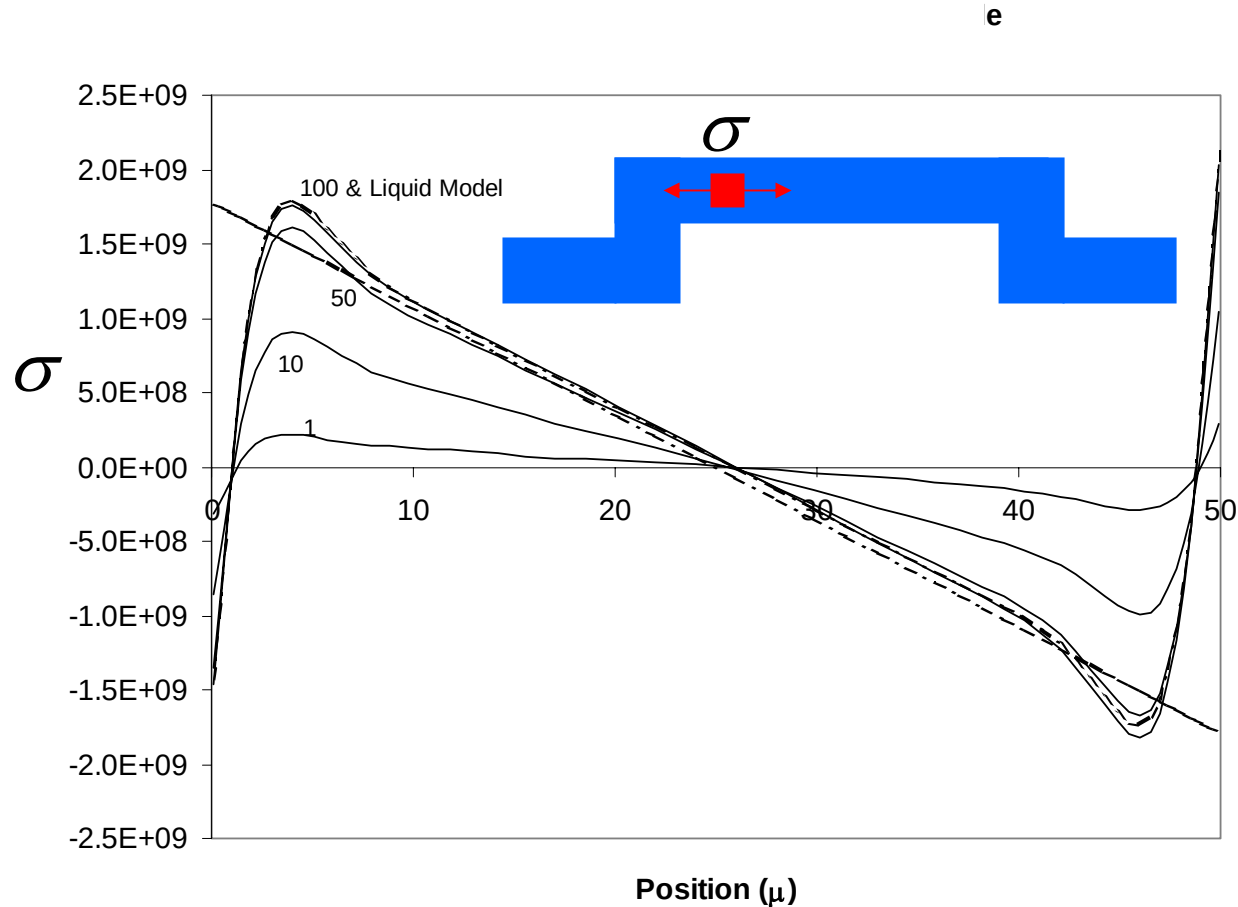
100 cycles



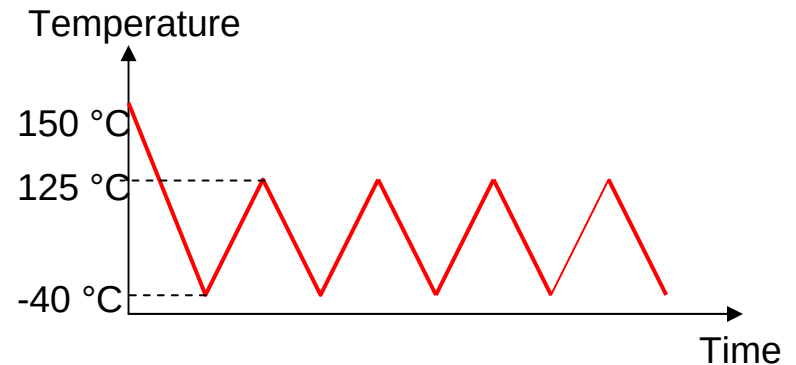
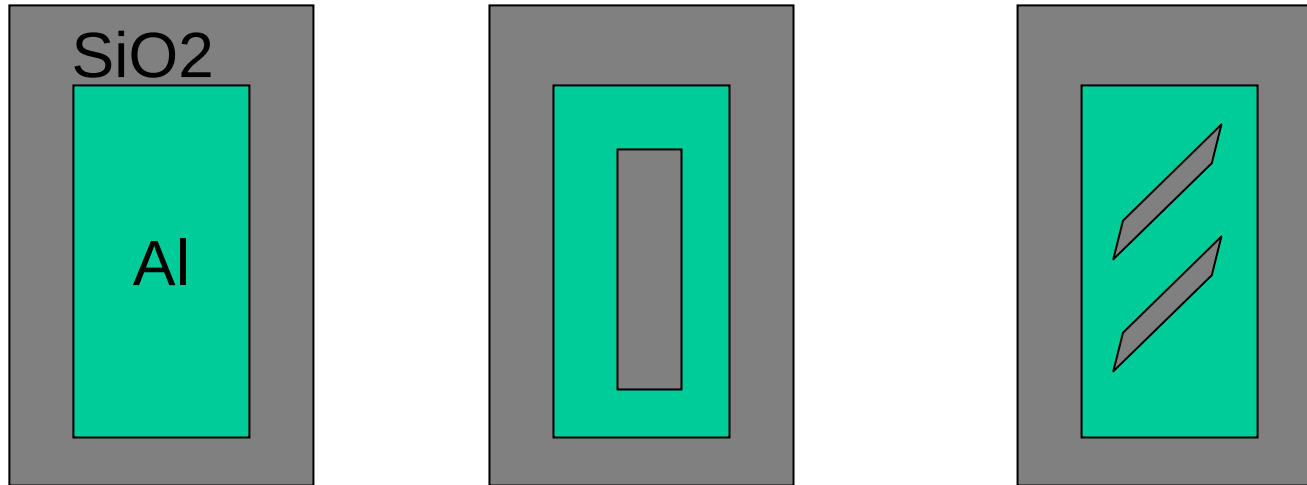
Shear stress in metal relaxes as temperature cycles



Membrane stress in SiN builds up as temperature cycles



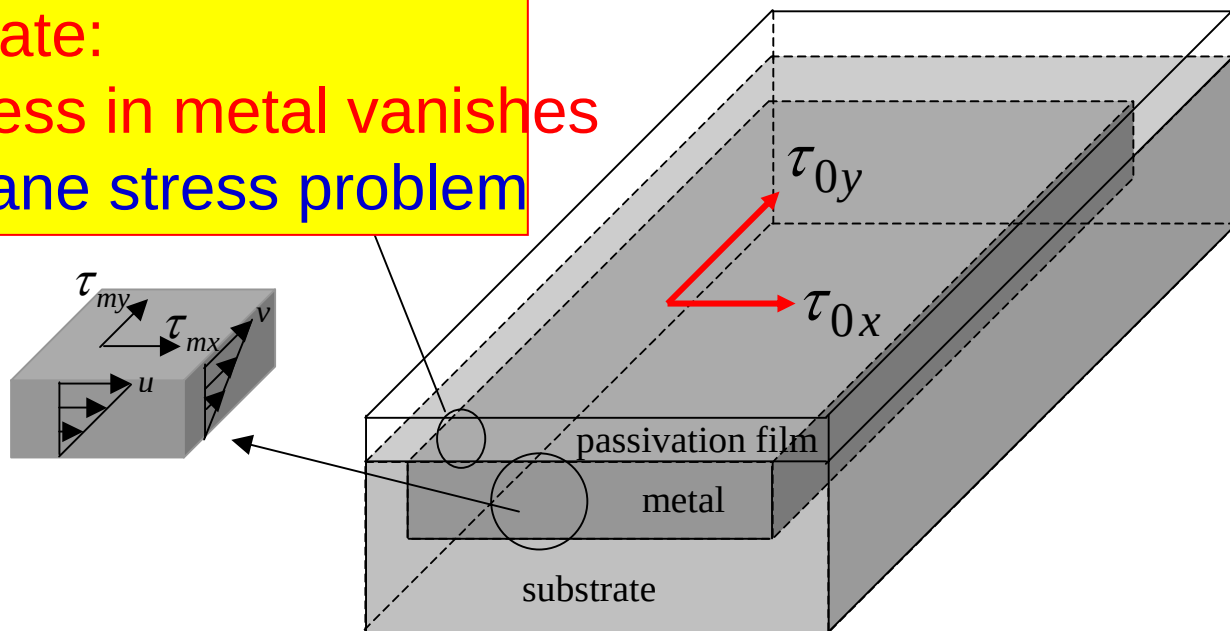
Metal pad geometry. Slots.



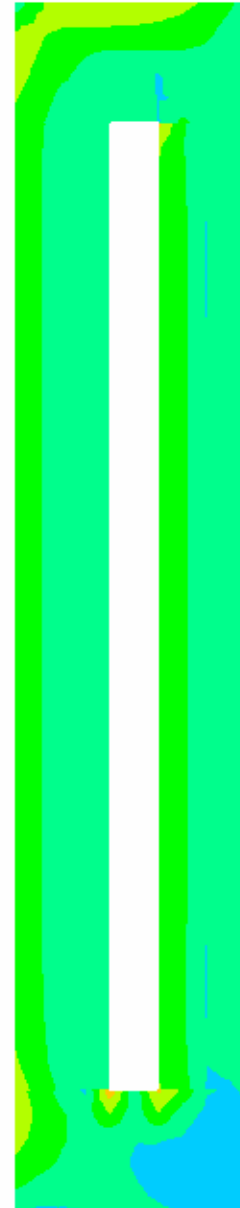
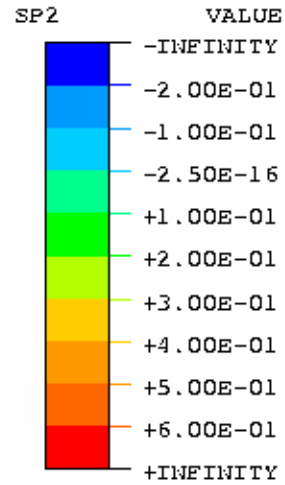
- Direct finite element calculations for 3D, many cycles take VERY long time.

3D Structure

Steady-state:
Shear stress in metal vanishes
Elastic plane stress problem



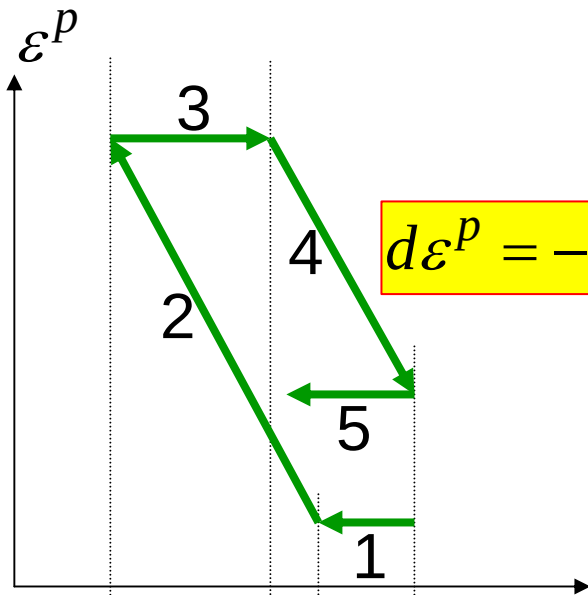
Slot!



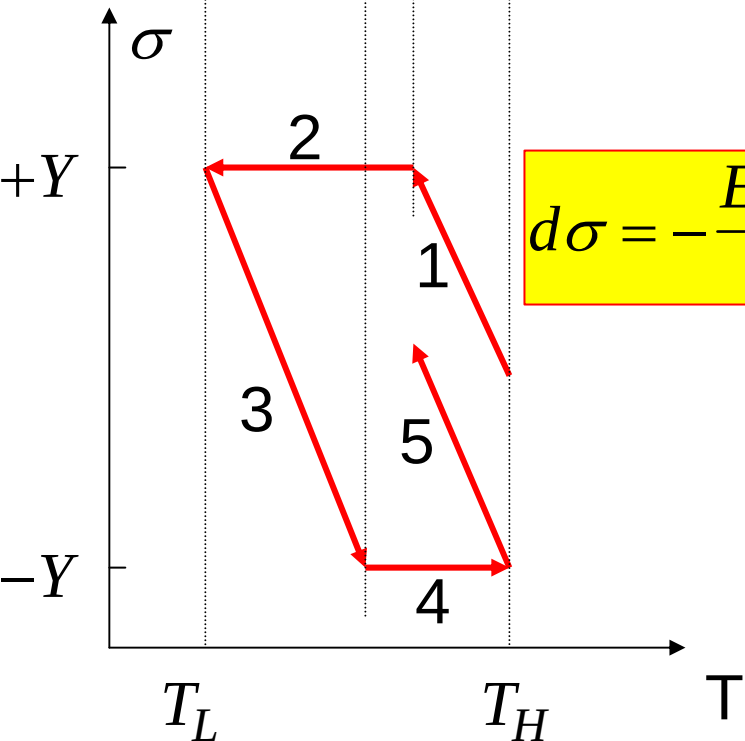
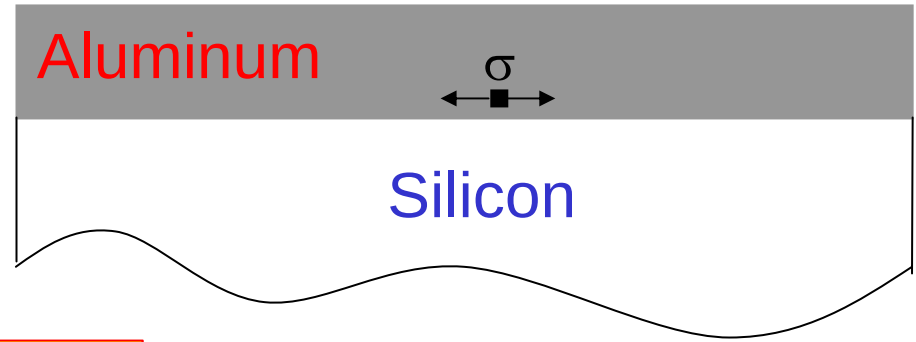
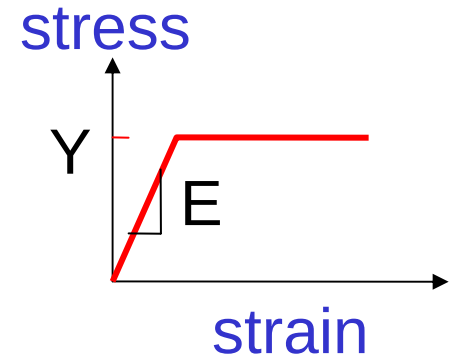
Further Issues

- Why cycle, again? Why not just plastic collapse?
- Number of cycles to approach the steady state.

Blanket film



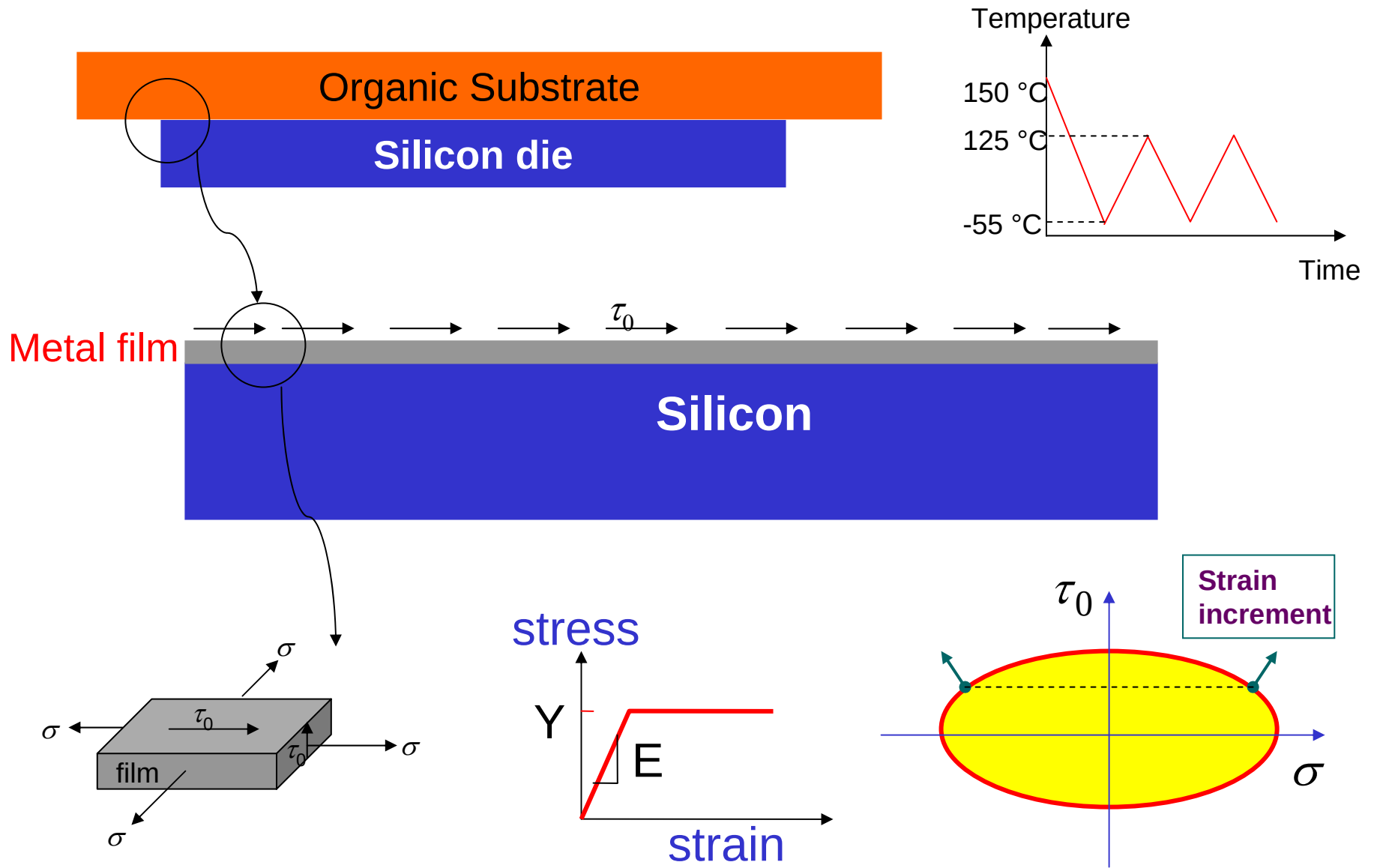
$$d\epsilon^p = -(\alpha_m - \alpha_s)dT$$



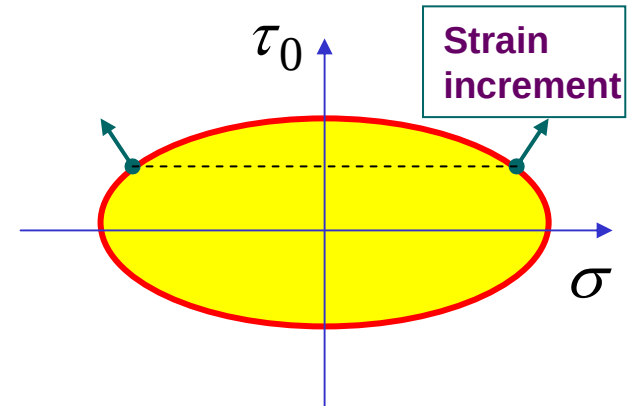
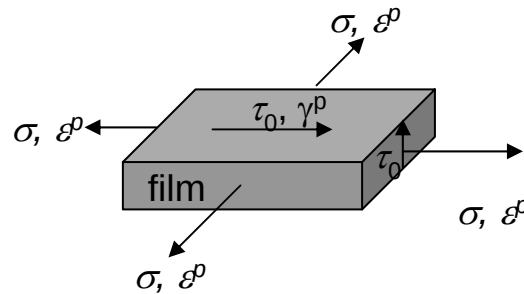
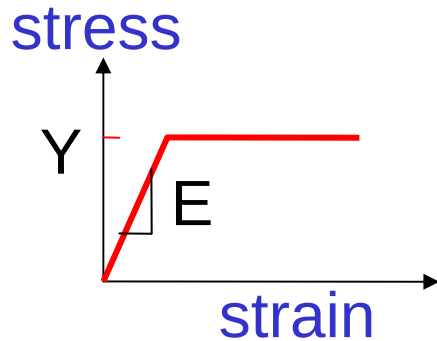
$$d\sigma = -\frac{E(\alpha_m - \alpha_s)}{1 - \nu}dT$$

$$\frac{E(T_H - T_L)(\alpha_f - \alpha_s)}{(1 - \nu)Y} \begin{cases} > 2, & \text{cyclic plasticity} \\ < 2, & \text{shakedown} \end{cases}$$

Why Crawling?



Elastic-Plastic Model



$$\sigma^2 + 3\tau_0^2 = Y^2$$

Yield condition

Matching strains
of film & substrate

$$d\varepsilon^p = -(\alpha_f - \alpha_s)dT$$

J2 flow theory

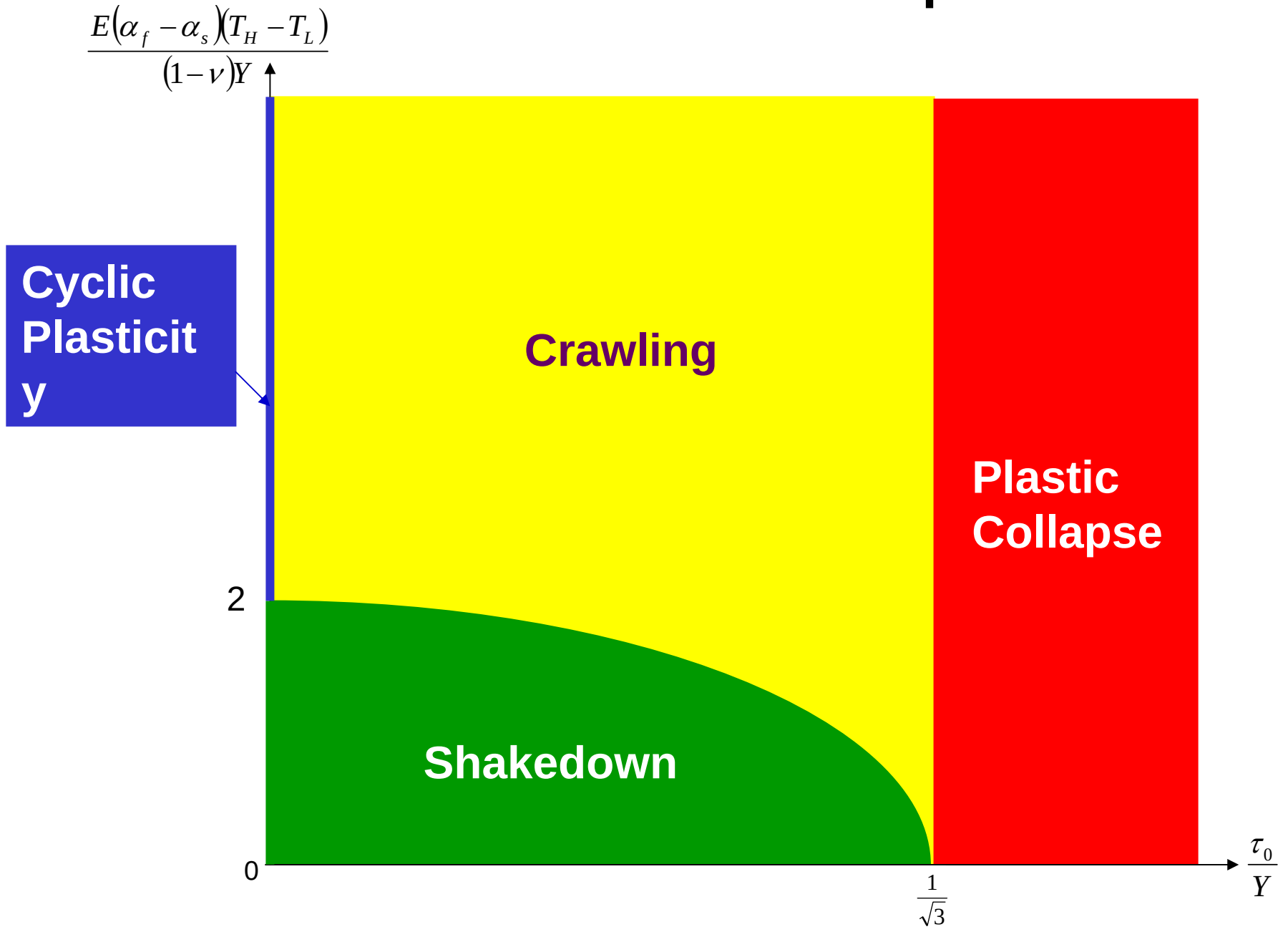
$$d\varepsilon_{ij}^p = s_{ij}d\lambda$$

$$\frac{d\varepsilon^p}{\sigma/3} = \frac{d\gamma^p}{2\tau_0}$$

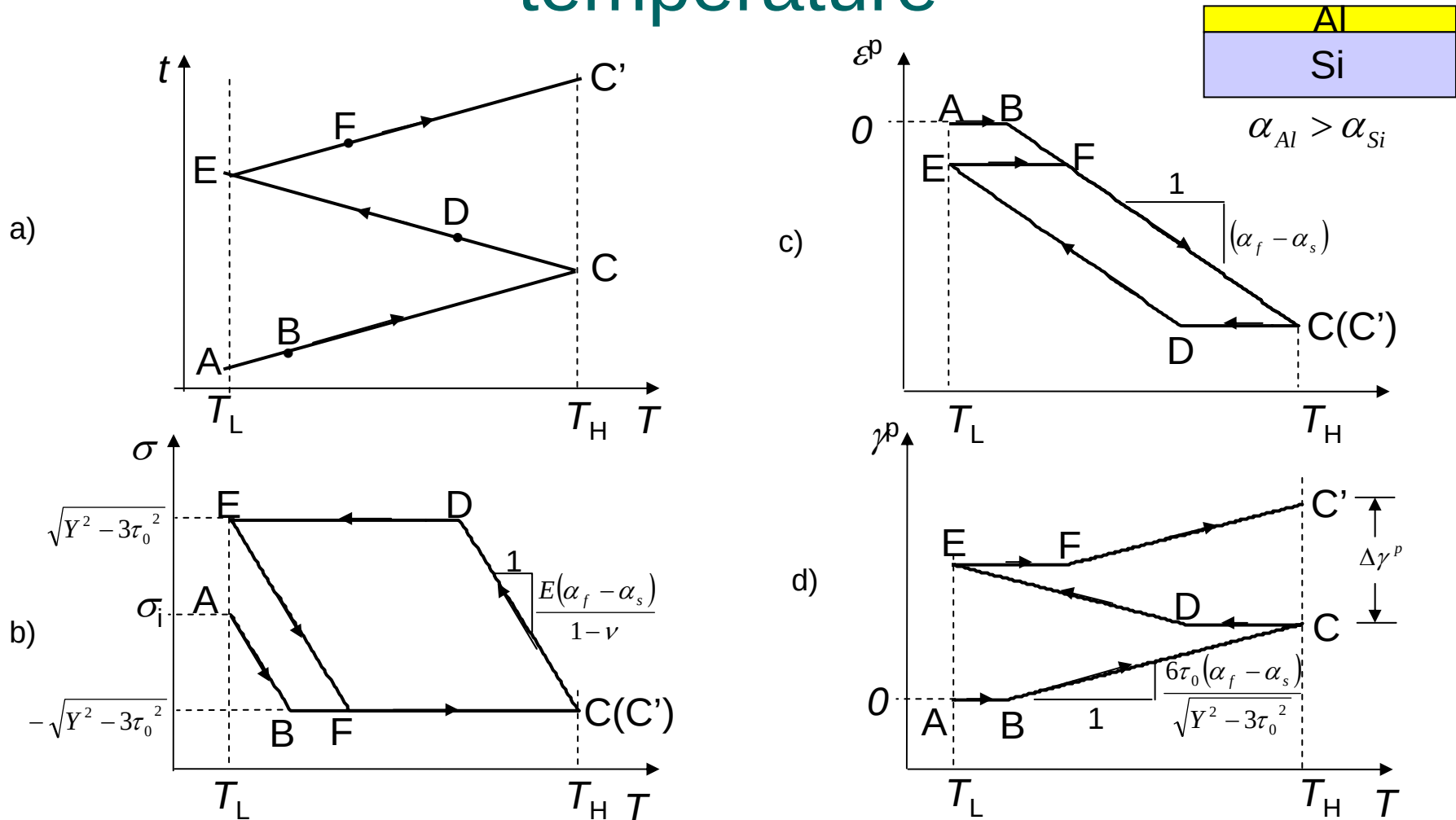
Shear strain increment

$$d\gamma^p = -\frac{6\tau_0}{\sigma}(\alpha_f - \alpha_s)dT$$

Four-color map

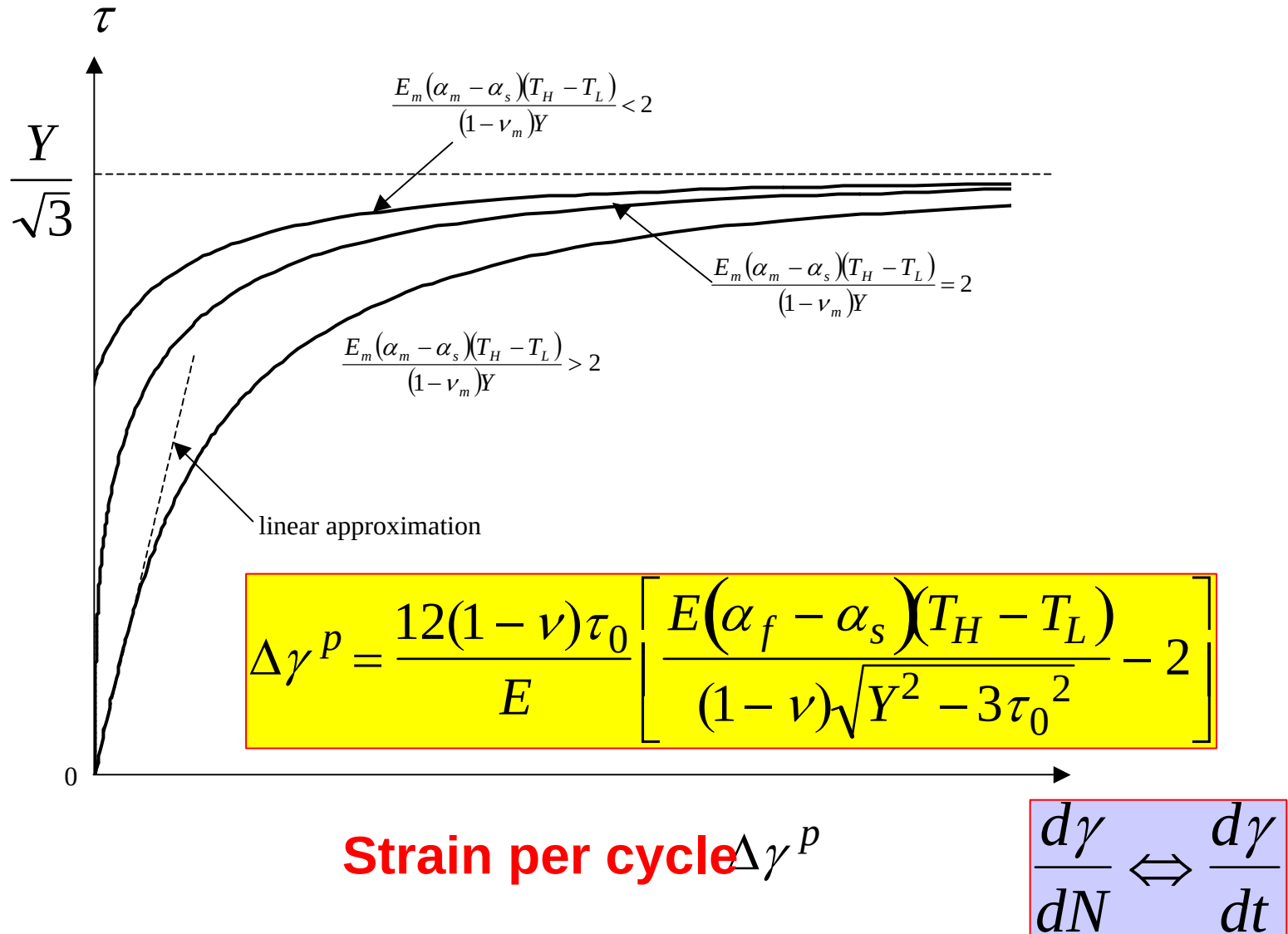


Stress and strain change with temperature

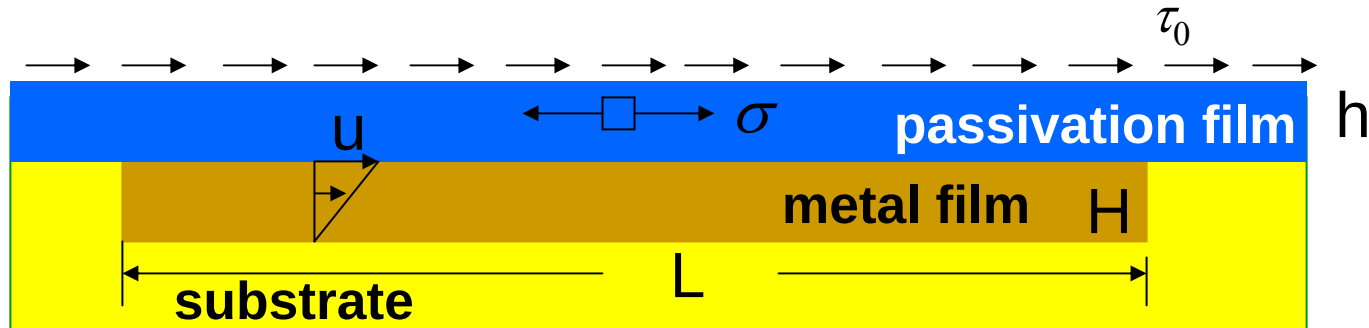


Strain per cycle $\Delta \gamma^p = \frac{12(1-\nu)\tau_0}{E} \left[\frac{E(\alpha_f - \alpha_s)(T_H - T_L)}{(1-\nu)\sqrt{Y^2 - 3\tau_0^2}} - 2 \right]$

Ratcheting-Creep Analogy



Number of cycles to reach steady-state



Elastic passivation film

Equilibrium
$$h \frac{\partial \sigma}{\partial x} = \tau - \tau_0$$

Elasticity
$$\sigma = E_p \frac{\partial u}{\partial x}$$

Ratcheting metal film

$$\tau = \frac{\eta}{H} \frac{\partial u}{\partial N}$$

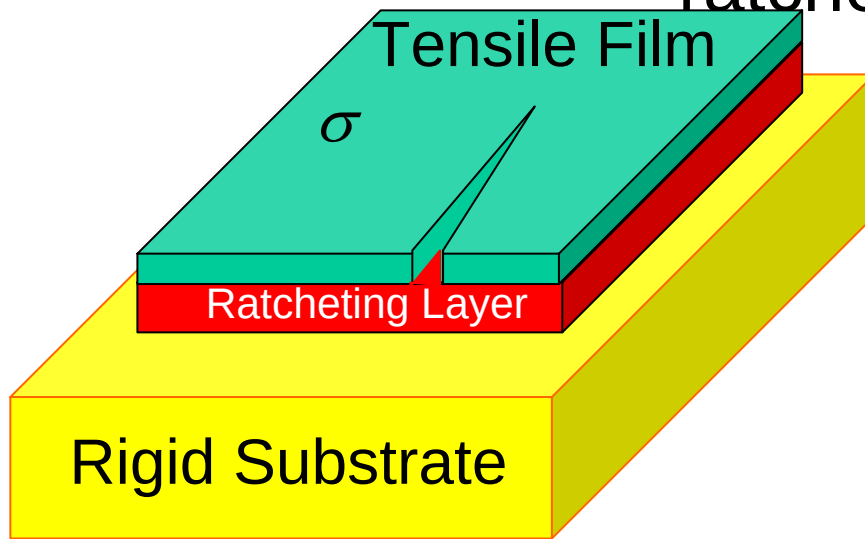
$$\eta = \frac{E_m}{12} \left(\frac{E_m \Delta \alpha \Delta T}{Y} - 2 \right)^{-1}$$

$$\frac{\partial u}{\partial N} = D \frac{\partial^2 u}{\partial x^2} - \frac{H \tau_0}{\eta}$$

$$D = \frac{E H h}{\eta}$$

$$N_0 \sim \frac{L^2}{D} \sim \frac{L^2}{H h} \frac{E_m}{E_p} \left(\frac{E_m \Delta \alpha \Delta T}{Y} - 2 \right)^{-1}$$

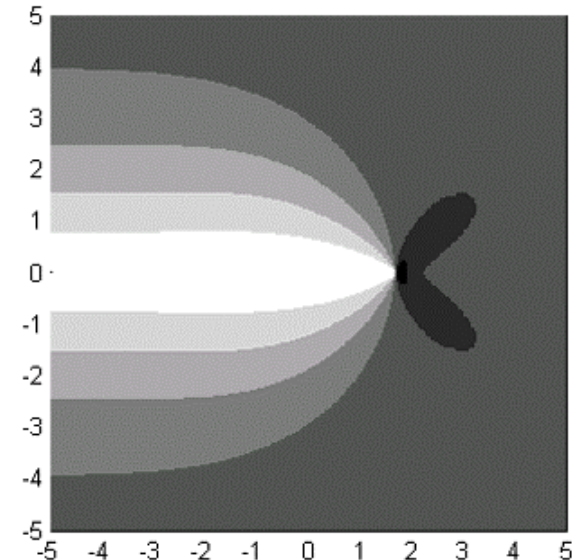
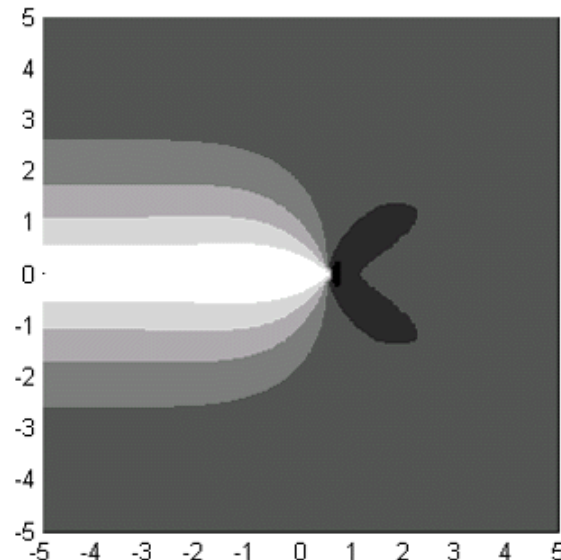
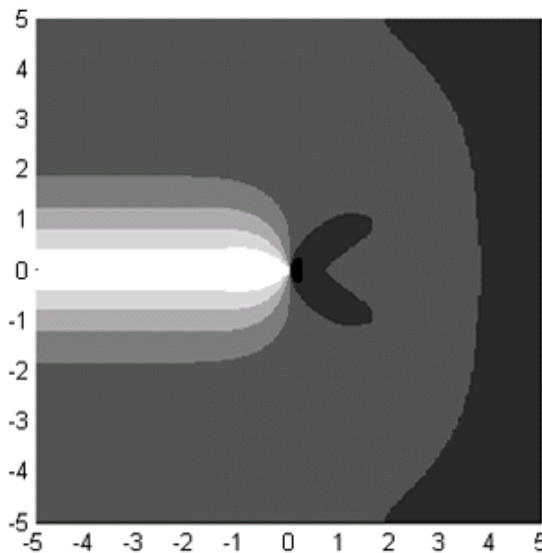
Concomitant crack extension and underlayer ratcheting



$$\frac{da}{dN} = 0.6 \frac{Hh\sigma^2}{\eta G_c}$$

$$\eta = \frac{E_m}{12(1-\nu_m)} \left[\frac{E_m \Delta \alpha \Delta T}{(1-\nu_m)Y} - 2 \right]^{-1}$$

J. Liang, R. Huang, J.H. Prevost, Z. Suo, submitted



Conclusions

- **Thermal cycling test is a bottleneck.**
- **Ratcheting:** cyclic temperature, aided by biased shear stress, causes uni-directional deformation.
- Stress relaxes in metal, and builds up in SiN.
- Ductile, low k dielectrics may ratchet.
- Need **thin film data** on large plastic deformation over many cycles, and long time